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DOCKET NO. 94-C-096C2

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : Kuei-Wu Huang, et al.

U.S. Serial No. : 09/517,987

Filed : March 3, 2000

For : METHOD OF FORMING PLANARIZED STRUCTURES IN
AN INTEGRATED CIRCUIT

Group No. : 2812

Examiner : R. Booth

Commissioner of Patents
and Trademarks
Washington, D. C. 20231

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CERTIFICATE OF MAILING

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Dear Sir:

TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT
BEFORE MAILING DATE OF EITHER A FINAL ACTION
OR NOTICE OF ALLOWANCE (37 CFR 1.97(c))

Time of Transmittal of Accompanying
Information Disclosure Statement

1. The Information Disclosure Statement transmitted herewith is being filed after the mailing date of the first Office Action on the merits.

The patents, publications and other information herein are listed below and on the attached Form PTO-1449. Copies of the listed references are submitted herewith.

02/01/2001 HLAKEH1 00000009 09517987

02 FC-126

180.00 OP

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<u>U.S. Patent No.</u>	<u>Inventor</u>	<u>Date</u>
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Publication

G. Quieirolo et al., "Dpoant Activation, Carrier Mobility, and TEM Studies in Polycrystalline Silicon Films," J. Electrochem. Soc. vol. 37, no. 3, pp. 967-970 (March 1990).

C.S. Pai et al, "Chemical Vapor Deposition of Selective Epitaxial Silicon Layers," J. Electrochem. Soc. vol. 137 no. 3, pp. 971-976 (March 1990).

Certification or Fee

2. Accompanying this transmittal is

— a certification as specified in 37 CFR 1.97(e)

OR

X the fee \$180.00 set forth in 37 CFR 1.17(p) for submission of an Information Disclosure Statement under §1.97(c).

Fee Payment

3. X Applicant elects the option to pay the fee set forth in 37 CFR 1.17(p) for submission of an Information Disclosure Statement under §1.97(c).

X Attached is a check in the amount of \$180.00.

4. — No fee required - 37 CFR 1.97(e) Certification enclosed.

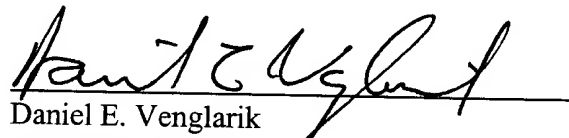
Applicant hereby expressly reserves the right to swear behind the effective dates of any of the above Patents and to question the relevance and materiality of the Patents and Publications listed herein, in whole, in part, or in combination, subsequent to filing this Information Disclosure Statement.

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PATENT

Respectfully submitted,

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Date: Jan 24, 2001


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